



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ065N06LS5		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA001425372						
<b>Package</b>		PG-TSDSON-8-26		<b>Weight*</b>		36.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.385	1.06	1.06	10551	10551
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		270	
	non noble metal	iron	7439-89-6	0.197	0.54		5396	
wire	non noble metal	copper	7440-50-8	7.988	21.91	22.49	219086	224819
	noble metal	gold	7440-57-5	0.028	0.08	0.08	765	765
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1025	
	plastics	epoxy resin	-	1.925	5.28		52799	
	inorganic material	silicondioxide	60676-86-0	16.729	45.87	51.25	458788	512612
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10841	10841
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	557	557
solder	non noble metal	tin	7440-31-5	0.012	0.03		335	
	noble metal	silver	7440-22-4	0.015	0.04		418	
	non noble metal	lead	7439-92-1	0.582	1.60	1.67	15972	16725
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
	non noble metal	iron	7439-89-6	0.094	0.26		2577	
	non noble metal	copper	7440-50-8	3.816	10.47	10.74	104654	107392
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		139	
	non noble metal	iron	7439-89-6	0.101	0.28		2778	
	non noble metal	copper	7440-50-8	4.112	11.28	11.57	112786	115738
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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